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PATENT TRADEMARK OFFICE

Patent
Case No.: 53434US009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: **HOGERTON, PETER B.**

Application No.: **09/690,600** Group Art Unit: **2827**

Filed: **October 17, 2000** Examiner: **Luan C. Thai**

Title: **SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING**

REQUEST FOR EXTENSION OF TIME UNDER 37 CFR § 1.136(a)

Commissioner for Patents
Washington, DC 20231

CERTIFICATE OF TRANSMISSION

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Date


Dean M. Harts

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Dear Sir:

This is a request for an extension of time under the provisions of 37 CFR § 1.136(a).

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- 37 CFR § 1.17(a)(1) - Extension within first month
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- 37 CFR § 1.17(a)(4) - Extension within fourth month.

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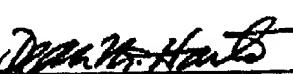
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Respectfully submitted,

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By: 
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04/02/2003 JNCMILLA 00000002 133723 09690600

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